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(54) **PACKAGE STRUCTURE AND METHOD FOR FORMING THE SAME**

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ABSTRACT

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A package structure including a first semiconductor die, at least one second semiconductor die conductive terminals and an insulating encapsulation is provided. The at least one second semiconductor die is stacked on and electrically connected to the first semiconductor die. The conductive terminals are disposed on and electrically connected to the first semiconductor die. The insulating encapsulation laterally encapsulates the first semiconductor die, the at least one second semiconductor die and the conductive terminals, wherein the conductive terminals protrude from a surface of the insulating encapsulation. Furthermore, a method for forming the above-mentioned is also provided.

